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## ON Semiconductor®

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**April 2015** 

## FDD390N15A

# N-Channel PowerTrench<sup>®</sup> MOSFET 150 V, 26 A, 40 m $\Omega$

#### **Features**

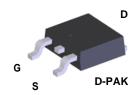
- $R_{DS(on)}$  = 33.5 m $\Omega$  ( Typ.) @  $V_{GS}$  = 10 V,  $I_D$  = 26 A
- · Fast Switching Speed
- Low Gate Charge, Q<sub>G</sub> = 14.3 nC( Typ.)
- High Performance Trench Technology for Extremely Low  $R_{DS(on)}$
- · High Power and Current Handling Capability
- · RoHS Compliant

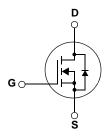
### **Description**

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

### **Applications**

- · Consumer Appliances
- LED TV
- · Synchronous Rectification
- · Uninterruptible Power Supply
- Micro Solar Inverter





#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol		Parameter		FDD390N15A	Unit	
V <sub>DSS</sub>	Drain to Source Voltage			150	V	
V	Cata to Source Voltage	- DC	- DC		V	
$V_{GSS}$	Gate to Source Voltage	- AC	(f > 1 Hz)	±30	] v	
I <sub>D</sub>	Drain Current	- Continuous (T <sub>C</sub> = 25°C, Silicon Limited)			^	
	Drain Current	- Continuous (T <sub>C</sub> = 100°C, Silicon	Limited)	17	Α	
I <sub>DM</sub>	Drain Current	- Pulsed	(Note 1)	104	Α	
E <sub>AS</sub>	Single Pulsed Avalanche En	Single Pulsed Avalanche Energy (Note 2)		78	mJ	
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	6.0	V/ns	
<b>C</b>	Dower Dissipation	$(T_C = 25^{\circ}C)$		63	W	
$P_{D}$	Power Dissipation  - Derate above 25°C			0.5	W/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temp	perature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperature 1/8" from Case for 5 Second			300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	FDD390N15A	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	2.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	87	· C/VV

## **Package Marking and Ordering Information**

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDD390N15A	FDD390N15A	DPAK	Tape and Reel	330 mm	16 mm	2500 units

## **Electrical Characteristics** $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 μA, Referenced to 25°C	-	0.1	-	V/°C
1	Zoro Coto Voltago Proin Current	V <sub>DS</sub> = 120 V, V <sub>GS</sub> = 0 V	-	-	1	
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 120 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	500	μА
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA

#### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	-	4.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 10 \text{ V}, I_D = 26 \text{ A}$	-	33.5	40	mΩ
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 26 A	-	33	-	S

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	75 77 77 077	-	965	1285	pF
Coss	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V}$ 	\-	96	130	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	-\	5.8	-	pF
C <sub>oss(er)</sub>	Energy Related Output Capacitance	V <sub>DS</sub> = 75 V, V <sub>GS</sub> = 0 V		169	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V		-	14.3	18.6	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	$V_{DS} = 75 \text{ V}, I_D = 27 \text{ A}$		5.0	-	nC
Q <sub>gs2</sub>	Gate Charge Threshold to Plateau	V <sub>GS</sub> = 10 V	-	2.0	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge	(Note 4)	-	3.5	-	nC
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz	-	1.4	-	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		-	14	38	ns
t <sub>r</sub>		$V_{DD} = 75 \text{ V}, I_{D} = 27 \text{ A}$	- /	10	30	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 4.7 \Omega$	-	20	50	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4)	-	5	20	ns

#### **Drain-Source Diode Characteristics**

I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current			-	26	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current			-	104	Α
$V_{SD}$	Drain to Source Diode Forward Voltage V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 26 A		-	-	1.25	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 27 A, V <sub>DD</sub> = 75 V	-	63	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100 \text{ A}/\mu\text{s}$	-	131	-	nC

#### Notes:

- Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. Starting  $T_J = 25^{\circ}C$ , L = 3 mH,  $I_{SD} = 7.2$  A
- 3.  $I_{SD} \le 26$  A, di/dt  $\le 200$  A/ $\mu s$ ,  $V_{DD} \le BV_{DSS}$ , Starting  $T_J = 25^{\circ}C$
- 4. Essentially Independent of Operating Temperature Typical Characteristics

## **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

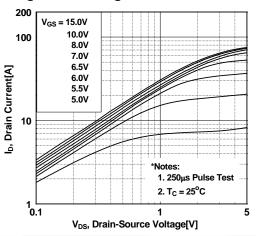


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

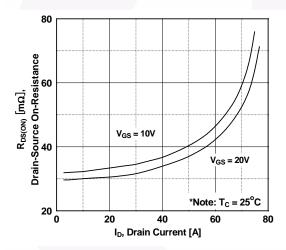


Figure 5. Capacitance Characteristics

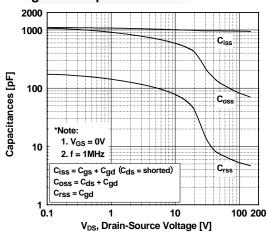


Figure 2. Transfer Characteristics

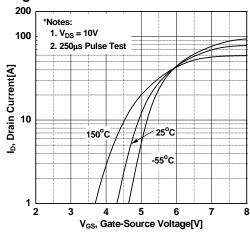


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

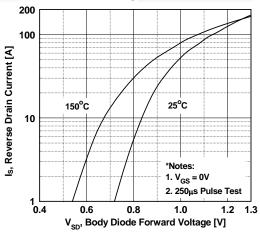
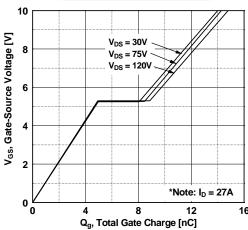


Figure 6. Gate Charge Characteristics



#### **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

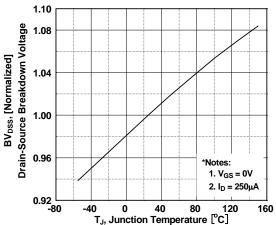


Figure 9. Maximum Safe Operating Area

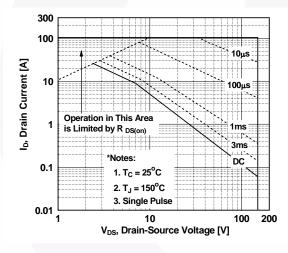


Figure 11. Eoss vs. Drain to Source Voltage

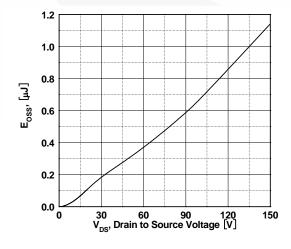


Figure 8. On-Resistance Variation vs. Temperature

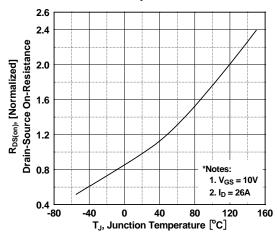


Figure 10. Maximum Drain Current vs. Case Temperature

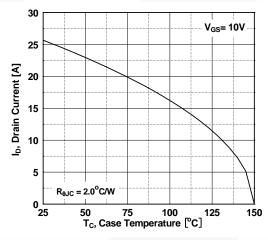
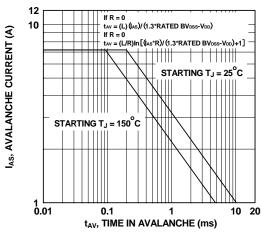
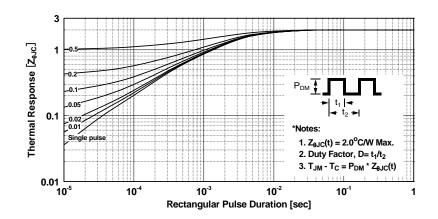


Figure 12. Unclamped Inductive Switching Capability



## **Typical Performance Characteristics** (Continued)

Figure 13. Transient Thermal Response Curve



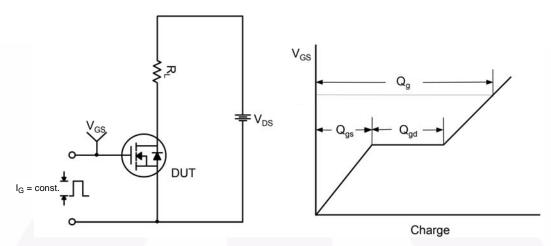


Figure 14. Gate Charge Test Circuit & Waveform

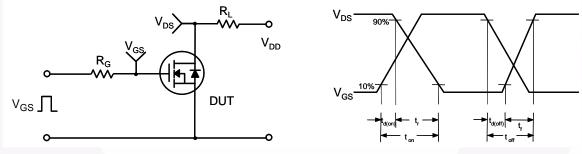


Figure 15. Resistive Switching Test Circuit & Waveforms

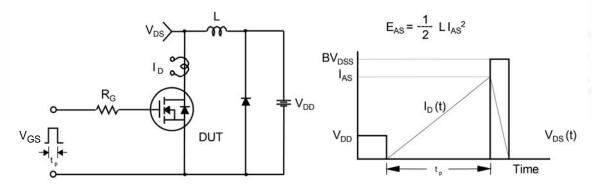


Figure 16. Unclamped Inductive Switching Test Circuit & Waveforms

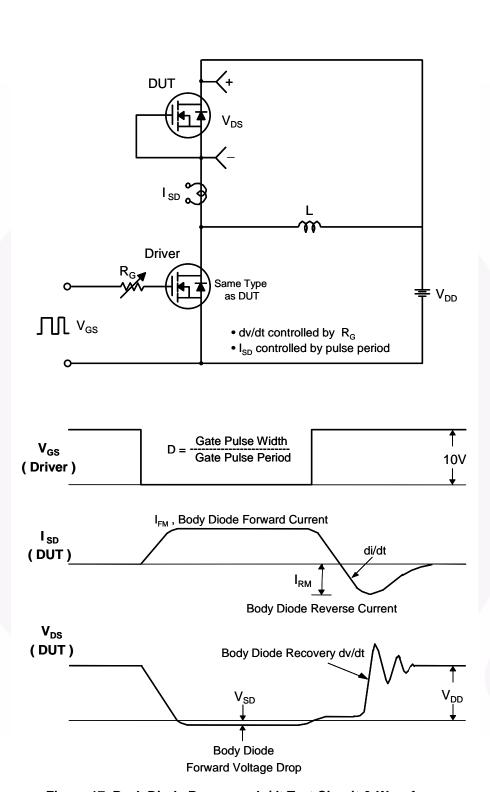


Figure 17. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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